

## 40V Full-Bridge of MOSFET

### Description

The HM6; 46D uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. The complementary MOSFETs may be used to form a H-Bridge, and for a host of other applications.

### General Features

- ◆ **N-channel:**  
 $V_{DS} = 40V, I_D = 10A$   
 $R_{DS(ON)} = 22m\Omega$  (typical) @  $V_{GS} = 4.5V$   
 $R_{DS(ON)} = 17m\Omega$  (typical) @  $V_{GS} = 10V$
- ◆ **P-Channel:**  
 $V_{DS} = -40V, I_D = -6A$   
 $R_{DS(ON)} = 65m\Omega$  (typical) @  $V_{GS} = -4.5V$   
 $R_{DS(ON)} = 45m\Omega$  (typical) @  $V_{GS} = -10V$
- ◆ Excellent gate charge x  $R_{DS(ON)}$  product(FOM)
- ◆ Very low on-resistance  $R_{DS(ON)}$
- ◆ 150 °C operating temperature
- ◆ Pb-free lead plating
- ◆ 100% UIS tested

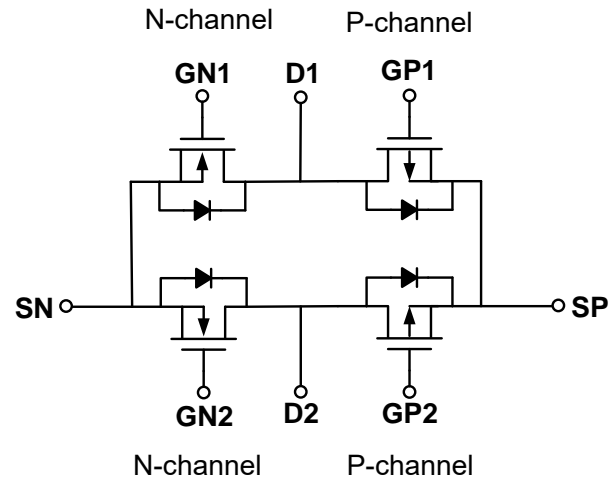
### Application

- ◆ Complementary MOSFET for DC FAN, Motor
- ◆ Wireless Charging

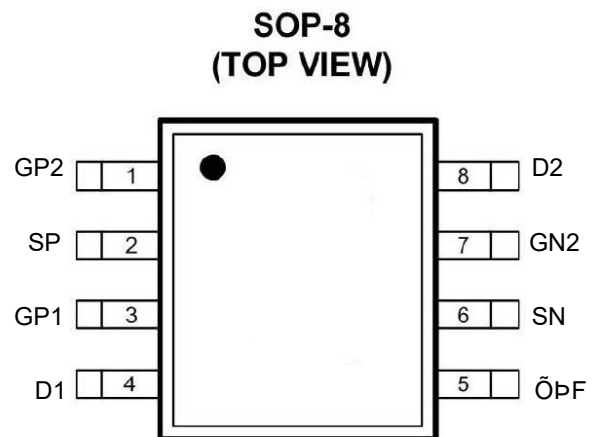
### Package

- ◆ SOP-8

### Schematic diagram



### Marking and pin assignment



### Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
HM6; 46DSR	-55°C to +150°C	SOP-8	3000
HM4924SF	-55°C to +150°C	SOP-8	4000

### Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Parameter	Symbol	Limit		Unit
		N	P	
Drain-source voltage	$V_{DS}$	40	-40	V

Gate-source voltage	$V_{GS}$	$\pm 12$	$\pm 12$	V	
Maximum power dissipation	$P_D$	2.0	2.0	W	
Operating junction Temperature range	$T_J$	-55—150	-55—150	°C	
Drain Current-Continuous (Silicon Limited)	$T_A=25^\circ\text{C}$	$I_D$	10	-6	A
	$T_A=75^\circ\text{C}$		7	-4.2	
Pulsed Drain Current (Package Limited)	$I_{DM}$	30	-18	A	
Power Dissipation <sup>B</sup>	$T_A=25^\circ\text{C}$	$P_D$	2	2	W
	$T_A=75^\circ\text{C}$		1.3	1.3	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55—150		°C	

### N-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF Characteristics</b>						
Drain-source breakdown voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu\text{A}$	40	-	-	V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=40V, V_{GS}=0V$	-	-	1	$\mu\text{A}$
Gate-body leakage	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 12V$	-	-	$\pm 100$	nA
<b>ON Characteristics</b>						
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0		2.5	V
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=10A$	-		22	m $\Omega$
		$V_{GS}=10V, I_D=2.8A$	-		17	
Forward transconductance	$g_{fs}$	$V_{GS}=5V, I_D=10A$	-	5	-	S
<b>Dynamic Characteristics</b>						
Input capacitance	$C_{ISS}$	$V_{DS}=10V, V_{GS}=0V$ $f=1.0\text{MHz}$	-	240	-	pF
Output capacitance	$C_{OSS}$		-	45	-	
Reverse transfer capacitance	$C_{RSS}$		-	23	-	
Gate resistance	$R_g$	$V_{GS}=0V, V_{DS}=0V,$ $f=1.0\text{MHz}$	-	3.3	4.9	$\Omega$
<b>Switching Characteristics</b>						
Turn-on delay time	$t_{D(on)}$	$V_{DD}=10V$ $R_L=3.3\text{ohm}$ $V_{GEN}=4.5V$ $R_{GEN}=6\text{ohm}$	-	2.3	-	ns
Rise time	$t_r$		-	3.1	-	
Turn-off delay time	$t_{D(off)}$		-	21	-	
Fall time	$t_f$		-	2.6	-	
Total gate charge	$Q_g$	$V_{DS}=10V$ $I_D=10A$ $V_{GS}=4.5V$	-	2.7	-	nC
Gate-source charge	$Q_{gs}$		-	0.4	-	
Gate-drain charge	$Q_{gd}$		-	0.5	-	

### Thermal Characteristics

Thermal Resistance junction-to ambient	$R_{th JA}$	100	°C/W
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### N-Channel: Typical Electrical And Thermal Characteristics

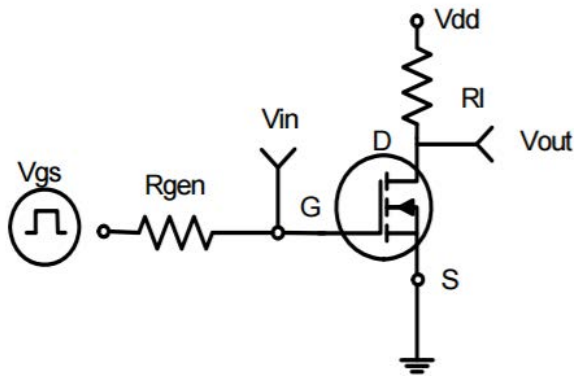


Figure 1: Switching Test Circuit

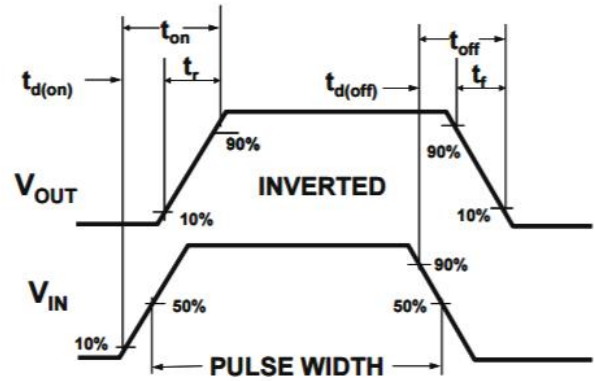


Figure 2: Switching Waveforms

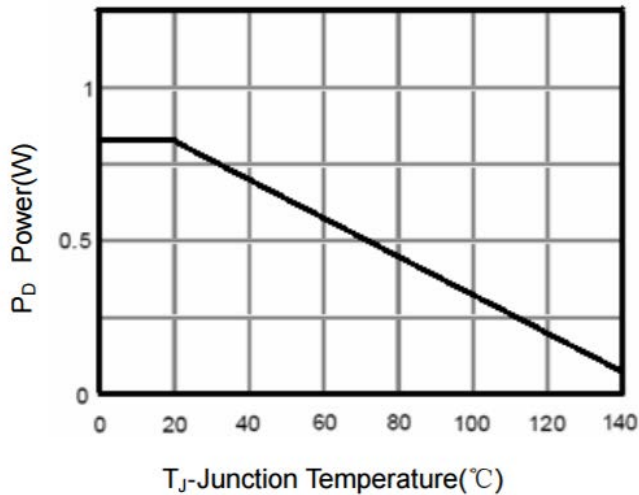


Figure 3 Power Dissipation

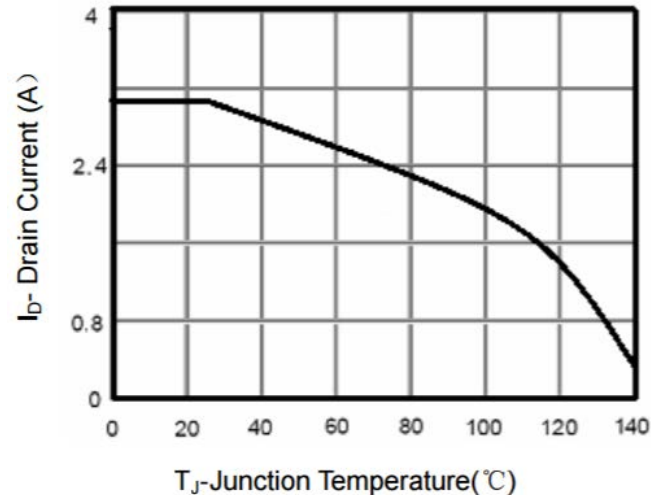


Figure 4 Drain Current

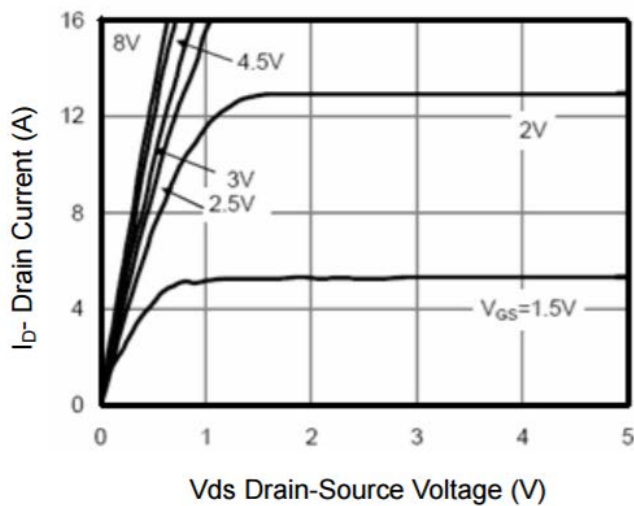


Figure 5 Output Characteristics

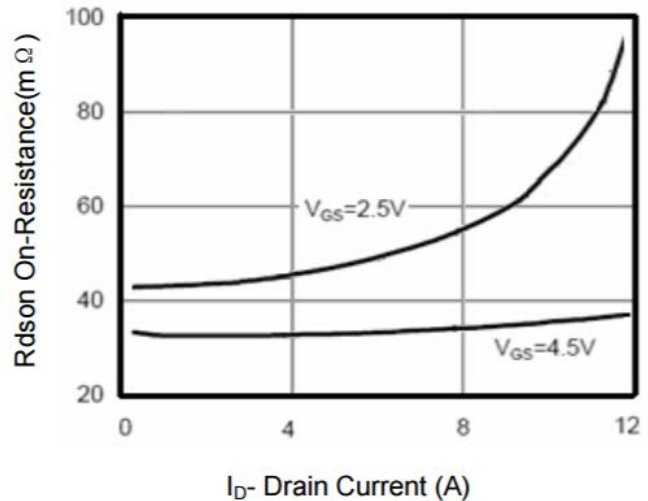


Figure 6 Drain-Source On-Resistance

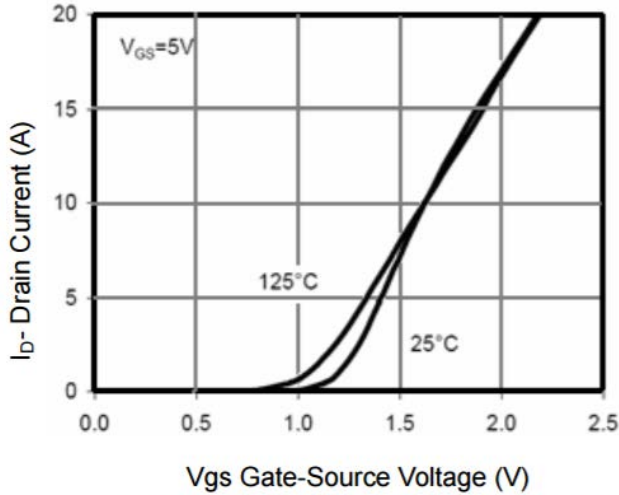


Figure 7 Transfer Characteristics

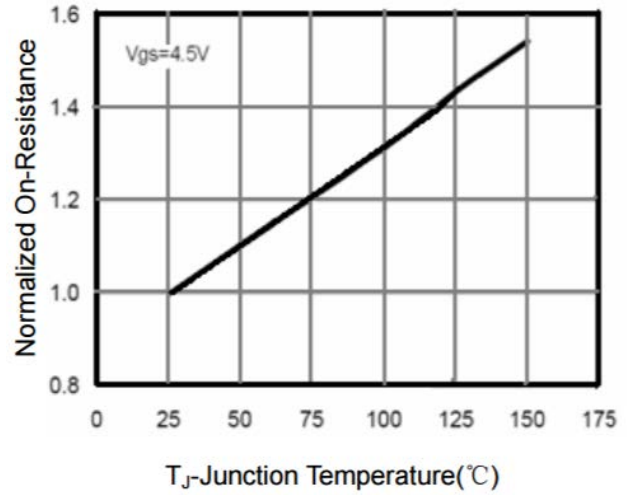


Figure 8 Drain-Source On-Resistance

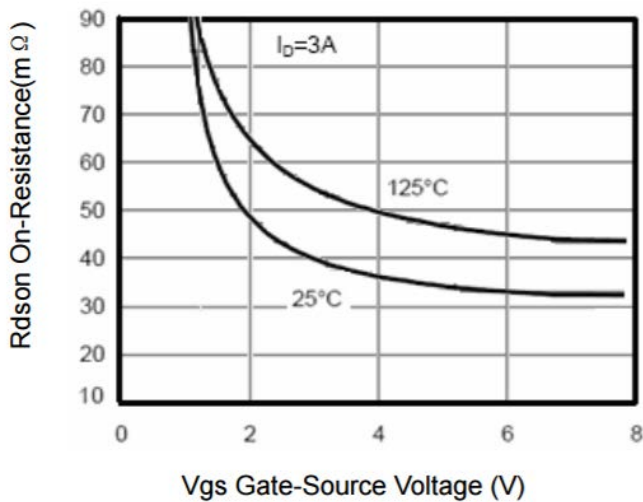


Figure 9 Rdson vs Vgs

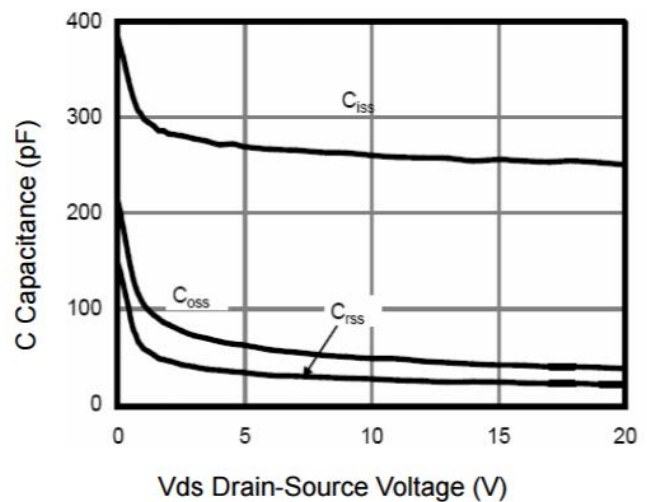


Figure 10 Capacitance vs Vds

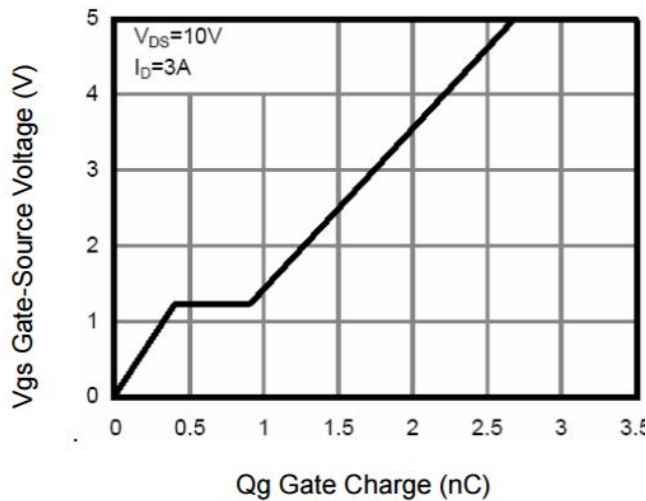


Figure 11 Gate Charge

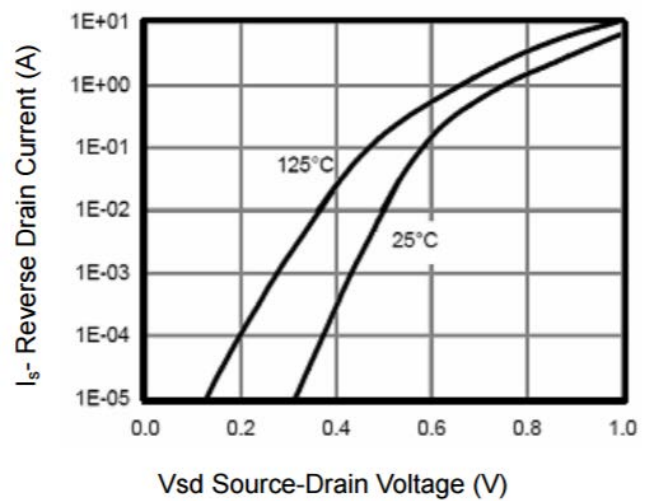


Figure 12 Source- Drain Diode Forward

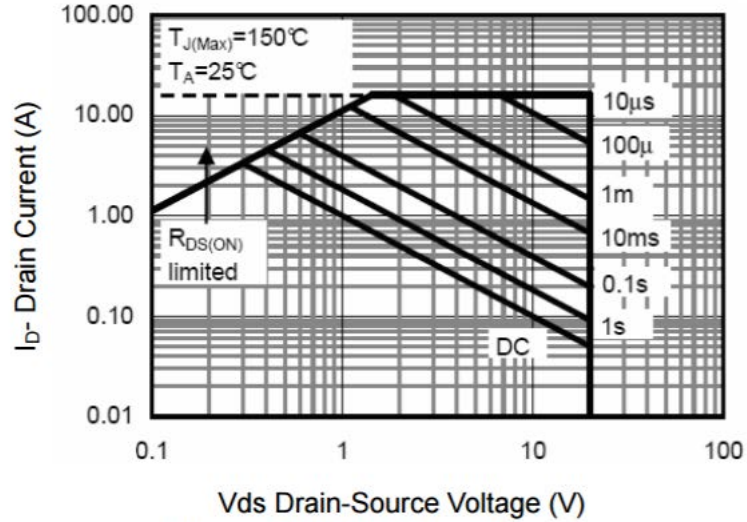


Figure 13 Safe Operation Area

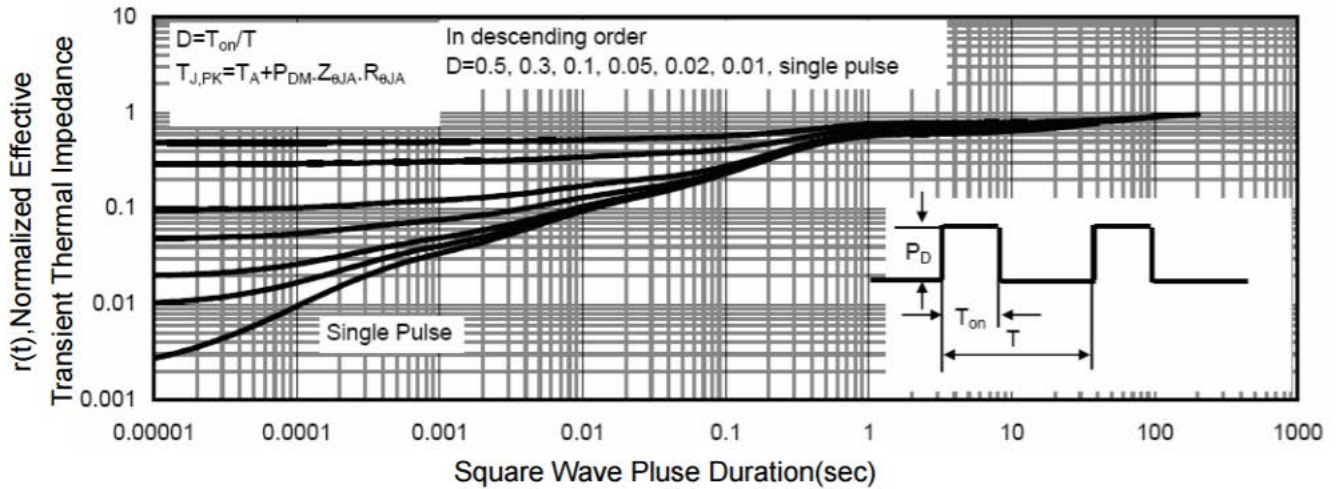
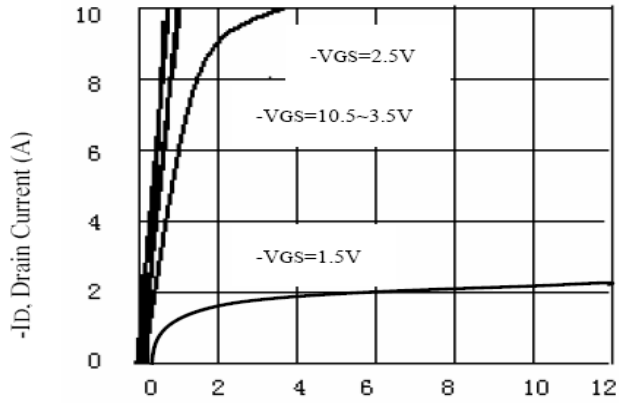


Figure 14 Normalized Maximum Transient Thermal Impedance

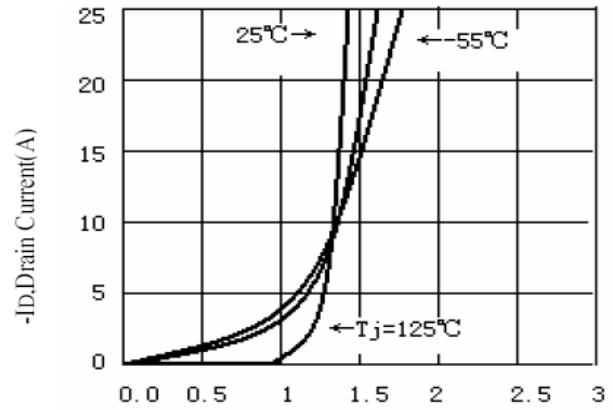
**P-Channel Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$  unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF Characteristics</b>						
Drain-source breakdown voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-40	-	-	V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=-40V, V_{GS}=0V$	-	-	-1	$\mu A$
Gate-body leakage	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 12V$	-	-	$\pm 100$	nA
<b>ON Characteristics</b>						
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.3		-2.5	V
Drain-source on-state resistance	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_D=-2.8A$	-		65	m $\Omega$
		$V_{GS}=-10V, I_D=-2.8A$	-		45	
Forward transconductance	gfs	$V_{GS}=-5V, I_D=-5A$	-	5	-	S
<b>Dynamic Characteristics</b>						
Input capacitance	$C_{ISS}$	$V_{DS}=-10V, V_{GS}=0V$ $f=1.0\text{MHz}$	-	561	-	pF
Output capacitance	$C_{OSS}$		-	61	-	
Reverse transfer capacitance	$C_{RSS}$		-	52	-	
<b>Switching Characteristics</b>						
Turn-on delay time	$t_{D(ON)}$	$V_{DD}=-10V$ $I_D=-2.8A$ $V_{GEN}=-4.5V$ $R_L=10\text{ohm}$ $R_{GEN}=-60\text{ohm}$	-	12.5	-	ns
Rise time	$t_r$		-	6.6	-	
Turn-off delay time	$t_{D(OFF)}$		-	113	-	
Fall time	$t_f$		-	46.6	-	
Total gate charge	Qg	$V_{DS}=-10V, I_D=-6A$ $V_{GS}=-4.5V$	-	6.1	-	nC
Gate-source charge	Qgs		-	1.7	-	
Gate-drain charge	Qgd		-	1.2	-	

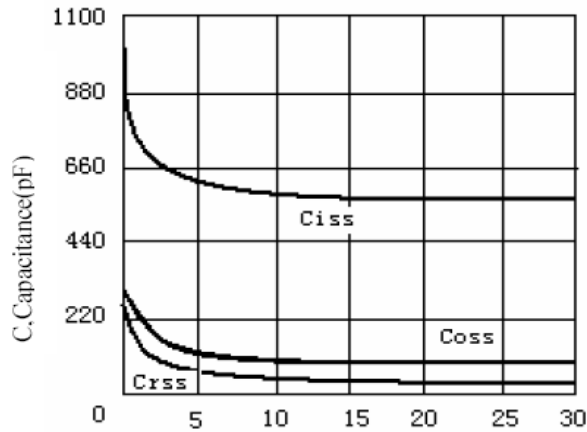
### P-Channel: Typical Electrical And Thermal Characteristics



- Vds, Drain-to-Source Voltage (V)  
Figure 1. Output Characteristics



-Vgs, Gate-to-source Voltage (V)  
Figure 2. Transfer Characteristics



- VGS, Drain-to Source Voltage  
Figure3. Capacitance

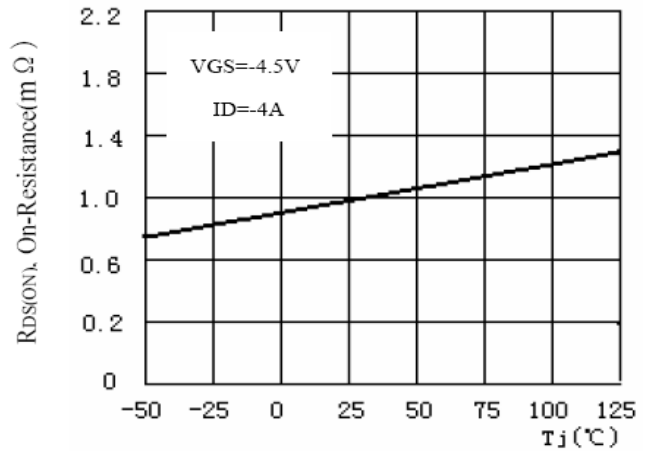
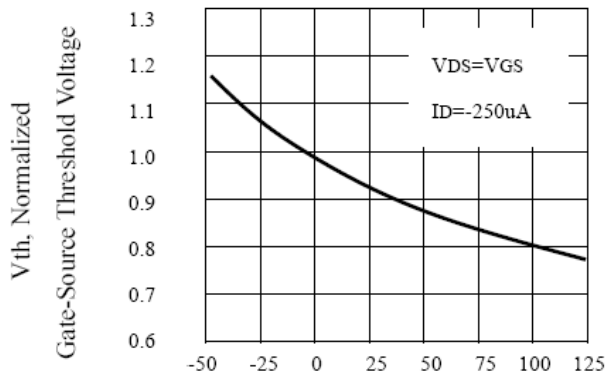
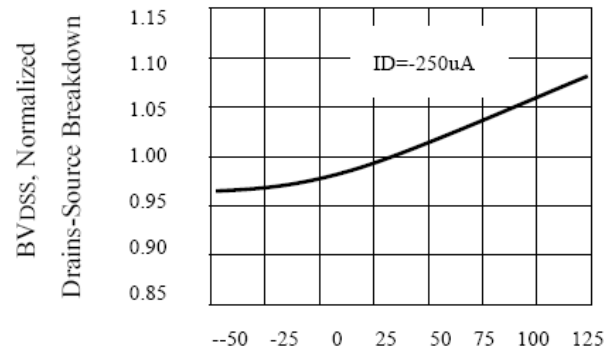


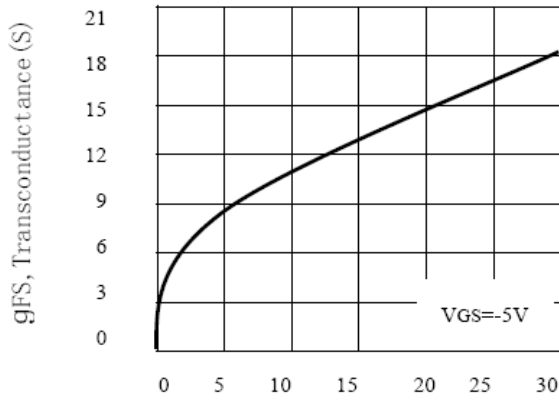
Figure4. On-Resistance Variation with Temperature



Tj, Junction Temperature(°C)  
Figure5. Gate Threshold Variation With Temperature

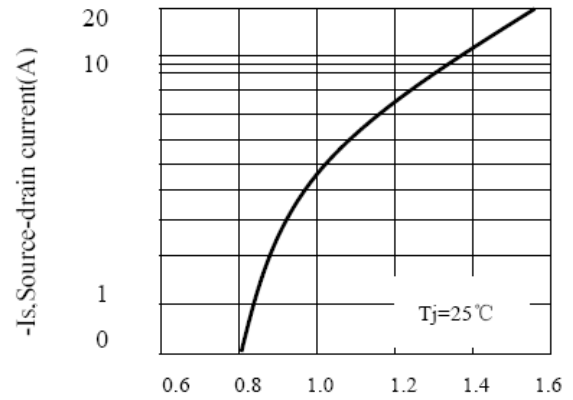


Tj, Junction Temperature (°C)  
Figure6. Breakdown Voltage Variation With Temperature



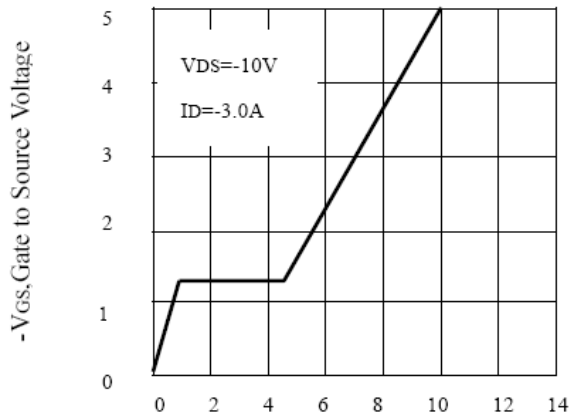
-IDS, Drain-Source Current (A)

Figure7. Transconductance Variation With Drain Current



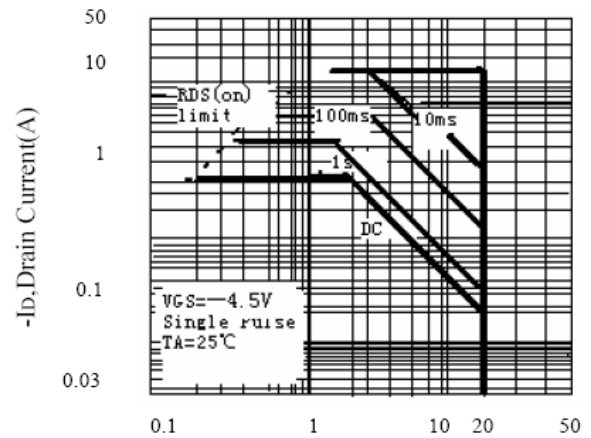
-VSD, Body Diode Forward Voltage

Figure8. Body Diode Forward Voltage Variation with Source Current



Qg, Total Gate Charge (nC)

Figure9. Gate Charge

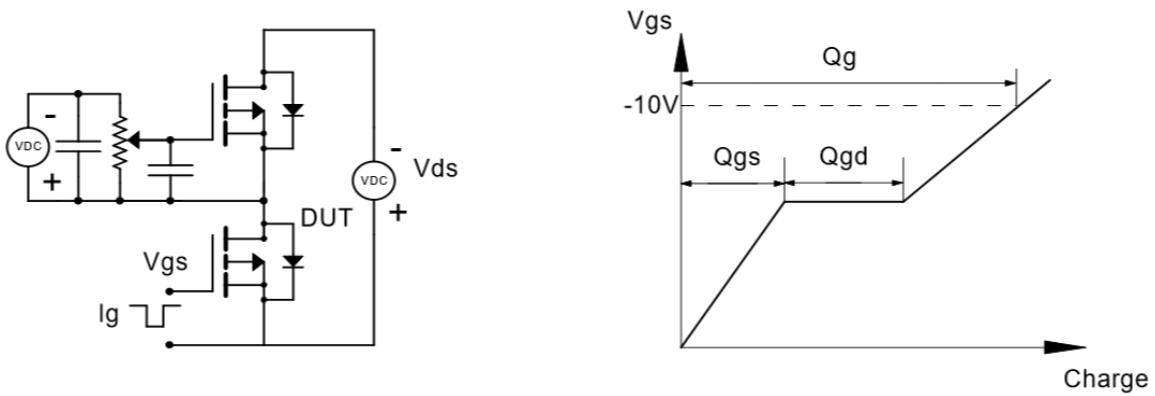


-VDS, Drain-Source Voltage(V)

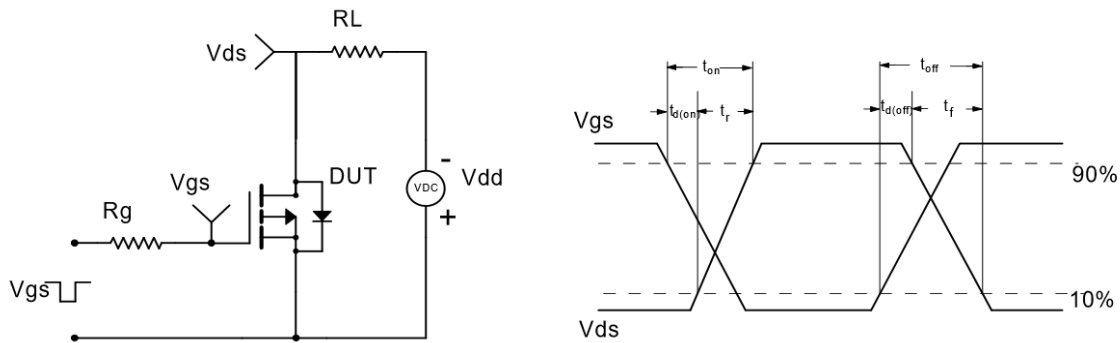
Figure10. Maximum Safe Operating Area



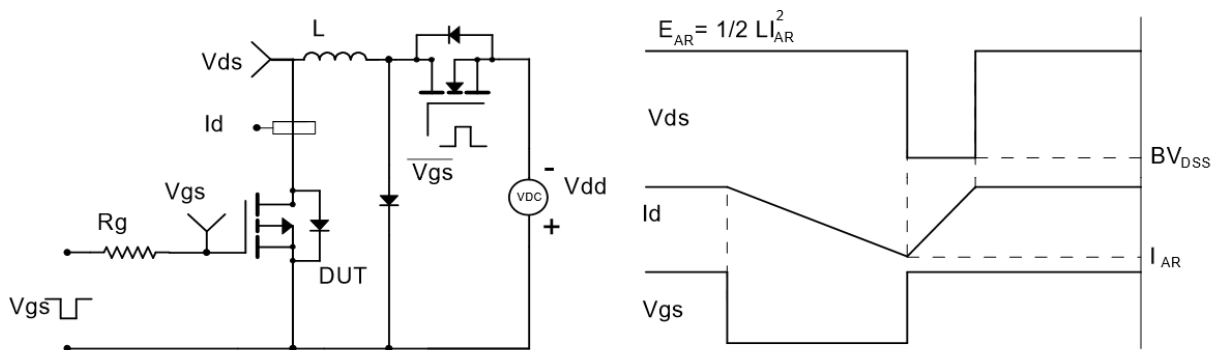
Gate Charge Test Circuit & Waveform



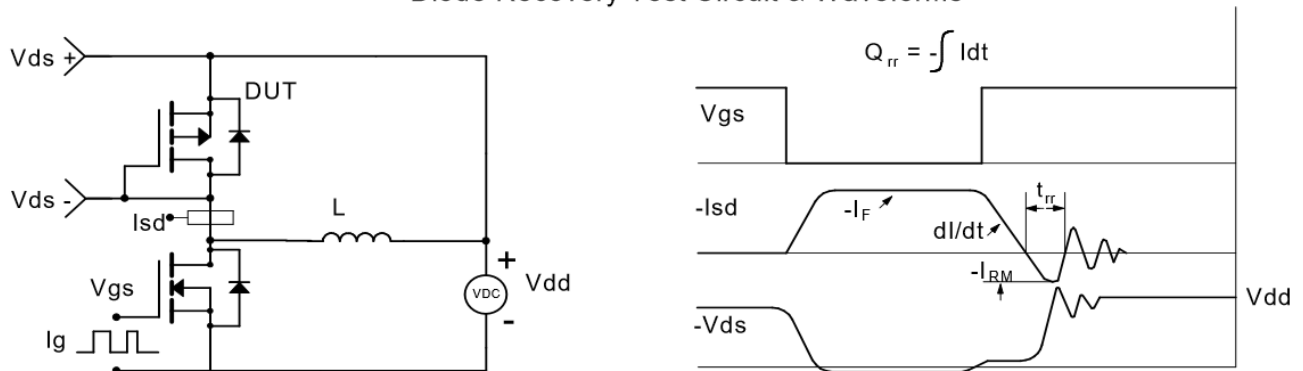
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

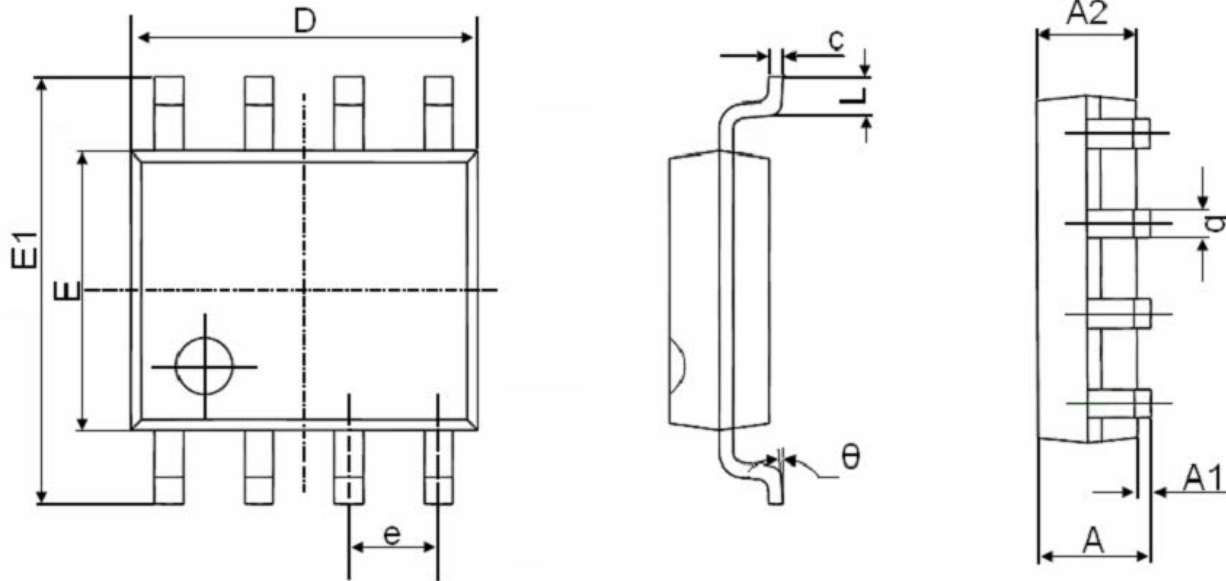


Diode Recovery Test Circuit & Waveforms



## Package Information

- SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
theta	0°	8°	0°	8°